

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Peng-Soon Lim</td> <td>06/25/2010</td> </tr> <tr> <td>Chia-Pin Lin</td> <td>06/25/2010</td> </tr> <tr> <td>Kuang-Yuan Hsu</td> <td>06/28/2010</td> </tr> </tbody> </table>		Name	Execution Date	Peng-Soon Lim	06/25/2010	Chia-Pin Lin	06/25/2010	Kuang-Yuan Hsu	06/28/2010
Name	Execution Date								
Peng-Soon Lim	06/25/2010								
Chia-Pin Lin	06/25/2010								
Kuang-Yuan Hsu	06/28/2010								
RECEIVING PARTY DATA									
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.								
Street Address:	No. 8, Li-Hsin R. 6, Science Based Industrial Park								
City:	Hsin-Chu								
State/Country:	TAIWAN								
Postal Code:	300-77								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13599507</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13599507				
Property Type	Number								
Application Number:	13599507								
CORRESPONDENCE DATA									
Fax Number:	2142000853								
Phone:	214-651-5000								
Email:	linda.ingram@haynesboone.com								
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>									
Correspondent Name:	HAYNES AND BOONE, LLP IP Section								
Address Line 1:	2323 Victory Avenue								
Address Line 2:	Suite 700								
Address Line 4:	Dallas, TEXAS 75219								
ATTORNEY DOCKET NUMBER:	24061.2273								
NAME OF SUBMITTER:	Rachel L.I. Davis								
Total Attachments: 2 source=2273_Assignment#page1.tif source=2273_Assignment#page2.tif									

OP \$40.00 13599507

Docket No.: 2010-0294 / 24061.1479  
Customer No.: 42717

**ASSIGNMENT**

WHEREAS, we,

- (1) Peng-Soon Lim of 27 Jalan 14/2, Taman Sri Kluang, 86000 Kluang  
Johor, Malaysia
- (2) Chia-Pin Lin of No. 32, Sec. 1, Yangxin Rd., Xinpu Township  
Hsinchu County 305, Taiwan R.O.C.
- (3) Kuang-Yuan Hsu of No. 7, Ln. 190, Beiyang Rd., Fongyuan City  
Taichung County 420, Taiwan, R.O.C.

have invented certain improvements in

**GATE STRUCTURES AND METHOD OF FABRICATING SAME**

for which we have executed an application for Letters Patent of the United States of America,

\_\_\_\_\_ of even date filed herewith; and  
  X   filed on June 30, 2010 and assigned application number 12/827,512; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu County 310, Taiwan, R.O.C., Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

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AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Peng-Soon Lim

Residence Address: 27 Jalan 14/2, Taman Sri Kluang, 86000 Kluang  
Johor, Malaysia

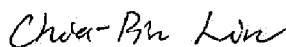
Dated: 6/25/2010

  
Inventor Signature

Inventor Name: Chia-Pin Lin

Residence Address: No. 32, Sec. 1, Yangxin Rd., Xinpu Township  
Hsinchu County 305, Taiwan R.O.C.

Dated: 6/25/2010

  
Inventor Signature

Inventor Name: Kuang-Yuan Hsu

Residence Address: No. 7, Ln. 190, Beiyang Rd., Fongyuan City  
Taichung County 420, Taiwan, R.O.C.

Dated: 6/28/2010

  
Inventor Signature